

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Bailey, et al.

Serial No: 09/452,691

Filed: 12/02/99



Docket No.: TI-27935-#3

Examiner: TBD

Art Unit: TBD

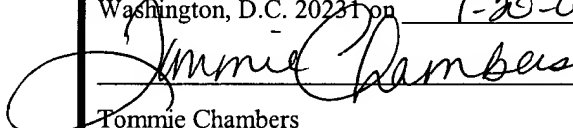
For: METHOD OF PRODUCING A THIN FILM RESISTOR IN AN INTEGRATED CIRCUIT

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.56

Asst. Commissioner
of Patents
Washington, DC 20231

CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)

I hereby certify that this correspondence is being deposited
with the U.S. Postal Service as First Class Mail in an envelope
addressed to: Assistant Commissioner of Patents,
Washington, D.C. 20231 on 1-20-00.


Tommie Chambers

Dear Sir:

An attached FORM 1449 includes a list of documents which Applicants believe are relevant to the subject patent application. A copy of each citation is enclosed with the FORM 1449. Submission of these references does not constitute an admission that these papers were publications prior to the filing of the instant application. Applicants submit these references to aid the Examiner in the examination of this application.

This Information Disclosure Statement is submitted prior to the mailing of a first Office Action on the merits pursuant to 37 C.F.R. § 1.97(b).

Please charge any fees in connection with the filing of this paper, including extension of time fees, to the Deposit Account No. 20-0668 of Texas Instruments Incorporated. This form is submitted in triplicate.

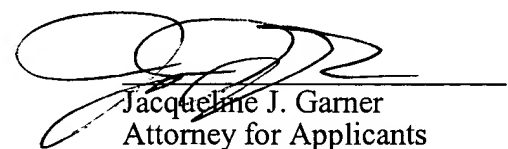
Respectfully submitted,

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